L Number	Hits	Search Text	DB	Time stamp
1	50	(copper near clad) same (laser near5 (carbon near dioxide))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/01/13 10:31
2	2	((copper near clad) same (laser near5 (carbon near dioxide))) and ((wav$2 or corrugat$3) same (copper near foil))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/01/13 10:14
3	494	((wav$2 or corrugat$3) same (copper near foil))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/01/13 09:36
4	15	(((wav$2 or corrugat$3) same (copper near foil))) same (copper near clad)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/01/13 09:36
5	205	(copper near3 particle) same (copper near foil)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/01/13 10:13
6	107	((copper near3 particle) same (copper near foil)) and (printed near circuit near board or "PCB" or printed near wiring near board or "PWB")	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/01/13 11:54
7	5	(((copper near3 particle) same (copper near foil)) and (printed near circuit near board or "PCB" or printed near wiring near board or "PWB")) and ((copper near clad) same (laser near5 (carbon near dioxide)))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/01/13 10:01
8	2500	(copper near2 laminate) same (copper near foil)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/01/13 10:14
9	24	((copper near2 laminate) same (copper near foil)) and ((wav$2 or corrugat$3) same (copper near foil))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/01/13 10:35
10	2	(((copper near2 laminate) same (copper near foil)) and ((wav$2 or corrugat$3) same (copper near foil))) and ((copper near clad) same (laser near5 (carbon near dioxide)))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/01/13 10:30
11	3	(((copper near2 laminate) same (copper near foil)) and ((wav$2 or corrugat$3) same (copper near foil))) and (laser near5 (carbon near dioxide))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/01/13 10:31
12	17	(bulk near copper) same (copper near foil)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/01/13 10:35
13	8	((bulk near copper) same (copper near foil)) and rough$3	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/01/13 10:36
14	1764	plat$3 same (copper near clad)	USPAT; US-PGPUB	2003/01/13 11:52

15	608	(plat$3 same (copper near clad)) and (resist same etch$3)	USPAT; US-PGPUB	2003/01/13 11:53
16	517	((plat$3 same (copper near clad)) and (resist same etch$3)) and (printed near circuit near board or "PCB" or printed near wiring near board or "PWB")	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/01/13 12:29
17	517	(((plat$3 same (copper near clad)) and (resist same etch$3)) and (printed near circuit near board or "PCB" or printed near wiring near board or "PWB")) and @pd<200000516	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/01/13 12:00
18	517	((plat$3 same (copper near clad)) and (resist same etch$3)) and (printed near circuit near board or "PCB" or printed near wiring near board or "PWB")	USPAT; US-PGPUB	2003/01/13 12:00
19	398	(((plat$3 same (copper near clad)) and (resist same etch$3)) and (printed near circuit near board or "PCB" or printed near wiring near board or "PWB")) and @pd<20000516	USPAT; US-PGPUB	2003/01/13 12:01
20	336	(via or hole or open$3) same (laser near (carbon near dioxide))	USPAT; US-PGPUB	2003/01/13 12:03
21	3	((((plat$3 same (copper near clad)) and (resist same etch$3)) and (printed near circuit near board or "PCB" or printed near wiring near board or "PWB")) and @pd<20000516) and ((via or hole or open$3) same (laser near (carbon near dioxide)))	USPAT; US-PGPUB	2003/01/13 12:04
22	2106	(printed near wiring near board or "PWB") and (plat$3 same via)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/01/13 12:43
23	3	((printed near wiring near board or "PWB") and (plat$3 same via)) and (bulk near copper)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/01/13 12:41
24	361	((printed near wiring near board or "PWB") and (plat$3 same via)) and (etch$3 same resist)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/01/13 12:44
25	172	(((printed near wiring near board or "PWB") and (plat$3 same via)) and (etch$3 same resist)) and @pd<20000516	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/01/13 12:45
26	3	((((printed near wiring near board or "PWB") and (plat$3 same via)) and (etch$3 same resist)) and @pd<20000516) and ((copper near clad) same laser)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/01/13 12:46